

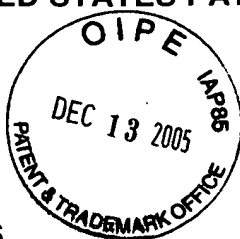
In re Application of:
Liu, et al.

Serial No.: 10/608,404

Confirmation No.: 7966

Filed: June 26, 2003

For: Method and Composition
for Polishing a Substrate



Group Art Unit: 1742

Examiner: Michael P. Alexander

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

CERTIFICATE OF MAILING
37 CFR 1.8

I hereby certify that this correspondence is being deposited on December 9, 2005, with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

December 9, 2005
Date

Brian K. Hrma

SUPPLEMENTAL RESPONSE TO OFFICE ACTION DATED JULY 12, 2005

In response to the Office Action dated July 12, 2005, having a shortened statutory period for response extended one month to expire on November 14, 2005, in which a response to the Office Action was timely filed, please enter this supplemental response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/5699.P3/BKH, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper. **Remarks** begin on page 10 of this paper.